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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/816,227	04/01/2004	Yoshikatsu Imazeki	9319S-000707	7313

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EXAMINER	
CHIU, TSZ K	
ART UNIT	**PAPER NUMBER**
2822	

DATE MAILED: 07/13/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)	
	10/816,227	IMAZEKI ET AL.	
	Examiner	Art Unit	
	Tsz K. Chiu	2822	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☒ Responsive to communication(s) filed on *28 April 2006*.

2a)☒ This action is **FINAL**. 2b)☐ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) *1-11 and 14* is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☒ Claim(s) *1-11 and 14* is/are rejected.

7)☐ Claim(s) _____ is/are objected to.

8)☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☐ The drawing(s) filed on _____ is/are: a)☐ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☒ All b)☐ Some * c)☐ None of:

1.☒ Certified copies of the priority documents have been received.

2.☐ Certified copies of the priority documents have been received in Application No. _____.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☐ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☒ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date *6-5-06*.
4) ☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application (PTO-152)
6) ☐ Other: _____.

DETAILED ACTION

Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

> The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claim 14 is rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. The protrusion parts of the protection layer did not discloses in the specification.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

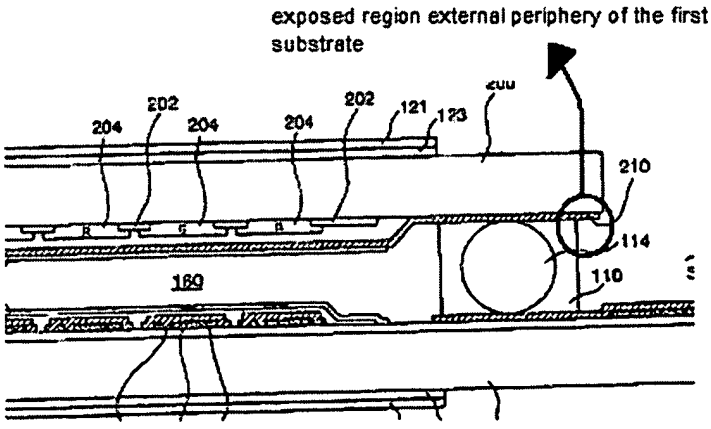
> A person shall be entitled to a patent unless –
>
> (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claim 1-11 rejected under 35 U.S.C. 102(b) as being anticipated by Hanakawa et al. (USPUB 2002/0005928).

With respect to claim 1 and 5, Hanakawa discloses in Fig. 2 a first substrate (200); a protection layer (205) formed on a part of the first substrate (200) leaving a region of the first substrate (right side of 200) wherein the protection layer is not formed; a first inter-substrate conduction unit formed (210) on the protection layer (205) a

second substrate (300) opposing the first substrate (200); a second inter-substrate conduction unit (left side of 350 below conductive particle 114) formed on the second substrate; a first wiring pattern (210) formed on the first substrate (200) and electrically connected to the first inter-substrate conduction unit (210); a metallic wiring pattern formed at a lower layer of the protection layer (205) and electrically connected to the first wiring pattern (210); a conductive member (114) for electrically connecting the first (210) and second inter-substrate (left side of 350 below conductive particle 114) units interposed between: the protection layer (205) and the first inter-substrate conduction unit (210) and the second inter-substrate conduction unit (left side of 350 below conductive particle 114); and a sealant (110) that contains the conductive member bonding the first substrate (200) and the second substrate (300) together by extending on both the protection layer (205) and the region (left side of the 110 region not for on first electrode) of the first substrate (200) where the protection layer (205) is not formed.

With respect to claim 2 and 8, Hanakawa discloses the exposed region of the first substrate where the protection layer (205) is not formed extends inboard from an external periphery of the first substrate (see drawing below).



With respect to claim 3 and 9, Hanakawa discloses a shape of the protection layer (205, For example Fig. 2) disposed at a bottom of the first inter-substrate conduction unit (210) is coordinated with a shape of the first inter-substrate conduction unit (210).

With respect to claim 4, Hanakawa discloses a color filter (204, For example Fig. 2) formed at a lower layer of the protection layer (205, For example Fig. 2) disposed on the first substrate (200, For example Fig. 2); and the first substrate (200, For example Fig. 2) is larger than the second substrate (300, For example Fig. 2) so that an extended region of the first substrate (200, For example Fig. 2) is produced when both the substrates (200,300, For example Fig. 2) are bonded together, and the extended region of the first substrate (200, For example Fig. 2) is provided with a mounting terminal to be connected to the first inter-substrate conduction unit (210, For example Fig. 2).

With respect to claim 6, Hanakawa discloses a material of the first wiring pattern (210) is the same as a material of the first inter-substrate conduction unit (210); and a resistance of the metallic wiring pattern (312) is smaller than a resistance of the first wiring pattern (210).

With respect to claim 7, Hanakawa discloses the metallic wiring pattern comprises any one of silver, a silver alloy, aluminum, and an aluminum alloy (page 1, paragraph 10).

With respect to claim 10, Hanakawa discloses in Fig. 2 a first substrate (200); a protection layer (205) formed a part of on the first substrate (200) leaving a region of the

first substrate (right side of 200) where the protection layer (205) is not formed; a first inter-substrate conduction unit formed (210) on the protection layer (205); a second substrate (300) opposing the first substrate (200); a second inter-substrate conduction unit (left side of 350 below conductive particle 114) formed on the second substrate; a conductive member (114) for electrically connecting the first (210) and second inter-substrate (left side of 350 below conductive particle 114) units interposed between: the protection layer (205) and the first inter-substrate conduction unit (210) and the second inter-substrate conduction unit (left side of 350 below conductive particle 114); and a sealant (110) having a fist region embracing the conductive member (114) and a second region with a thickness larger than the first region, the sealant (110) bonding the first substrate (200) and the second substrate (300) together.

With respect to claim 11, Hanakawa discloses an electronic instrument (page 1, paragraph 1) comprising an electro-optical device according to claim 1.

With respect to claim 14, Hanakawa discloses in Fig. 2 a first substrate (200); a protection layer (205) formed on a part of the first substrate (200) leaving a region of the first substrate (right side of 200) wherein the protection layer is not formed, the protection layer (205) having an outer edge defining a plurality of protrusion parts (outer edge of 205) of the protection layer; a first inter-substrate conduction unit formed (210) on the protection layer (205) a second substrate (300) opposing the first substrate (200); a second inter-substrate conduction unit (left side of 350 below conductive particle 114) formed on the second substrate; a first wiring pattern (210) formed on the first substrate (200) and electrically connected to the first inter-substrate conduction unit

(210); a metallic wiring pattern formed at a lower layer of the protection layer (205) and electrically connected to the first wiring pattern (210); a conductive member (114) for electrically connecting the first (210) and second inter-substrate (left side of 350 below conductive particle 114) units interposed between: the protection layer (205) and the first inter-substrate conduction unit (210) and the second inter-substrate conduction unit (left side of 350 below conductive particle 114); and a sealant (110) that contains the conductive member bonding the first substrate (200) and the second substrate (300) together by extending on both the protection layer (205) and the region (left side of the 110 region not for on first electrode) of the first substrate (200) where the protection layer (205) is not formed; wherein the region of the first substrate where the protection layer (205) is not formed includes a region between the protrusion parts (outer edge of 205), and the sealant (110) covers the outer edge of the protection layer (205) and the protrusion parts (outer edge of 205).

Response to Arguments

Applicant's arguments with respect to claim 1-11 and 14 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tsz K. Chiu whose telephone number is 517-272-8656. The examiner can normally be reached on 0800 to 1700.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra V. Smith can be reached on 571-272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

TC
July 10, 2006

Zandra V. Smith
Supervisory Patent Examiner
10 July 2006